

AMENDMENTS TO THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

1. (Cancelled)

2. (Cancelled)

3. (Currently Amended) An apparatus comprising:

an integrated circuit package;

an integrated circuit die coupled to the integrated circuit package;

a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed;

a thermally-conductive material disposed in the well and in contact with the stiffener portion and the integrated circuit die;

a thermally-conductive paste coupled to the stiffener portion and to the thermally-conductive material; and

a heat sink coupled to the thermally-conductive paste,

wherein the thermally conductive material is disposed between the integrated circuit die and the heat sink, and wherein the thermally-conductive paste is disposed between the heat sink and the thermally-conductive material.

~~a heat sink coupled to the stiffener portion and in contact with the thermally conductive material, the thermally conductive material disposed between the integrated circuit die and the heat sink.~~

4. (original) An apparatus according to Claim 3, further comprising:

underfill material disposed between the integrated circuit die and the integrated circuit package.

5. (Cancelled)

6. (Cancelled)

7. (Withdrawn) A method comprising:

placing a plurality of integrated circuit die on respective ones of a plurality of mounting locations of an integrated circuit package substrate; and

placing a stiffener strip on the integrated circuit package substrate,

wherein the plurality of integrated circuit die and the plurality of mounting locations are disposed in respective ones of a plurality of openings defined by the stiffener strip.

8. (Withdrawn) A method according to Claim 7, further comprising:

soldering the plurality of integrated circuit die to the respective mounting locations.

9. (Withdrawn) A method according to Claim 8, further comprising:

dispensing underfill material on the integrated package substrate adjacent to one or more of the mounting locations.

10. (Withdrawn) A method according to Claim 7, further comprising:

singulating one of the plurality of integrated circuit die and a respective mounting location of the integrated package substrate.

11. (Currently Amended) A system comprising:

a microprocessor comprising:

an integrated circuit package;

an integrated circuit die coupled to the integrated circuit package; and

a stiffener portion coupled to the integrated circuit package and surrounding the integrated circuit die, wherein the stiffener portion and the integrated circuit package define a well in which the integrated circuit die is disposed;

a thermally-conductive material disposed in the well and in contact with the stiffener portion and the integrated circuit die;

a thermally-conductive paste coupled to the stiffener portion and to the thermally-conductive material;

~~a heat sink coupled to the stiffener portion and in contact with the thermally-conductive material, the thermally-conductive material disposed between the integrated circuit die and the heat sink; and~~

a double data rate memory electrically coupled to the microprocessor; and

a heat sink coupled to the thermally-conductive paste,

wherein the thermally conductive material is disposed between the integrated circuit die and the heat sink, and wherein the thermally-conductive paste is disposed between the heat sink and the thermally-conductive material.

12. (Cancelled)

13. (Cancelled)

14. (original) A system according to Claim 11, further comprising:
a motherboard electrically coupled to the microprocessor and to the memory.